



PRODUCT DATA SHEET



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Datasheet



Resources



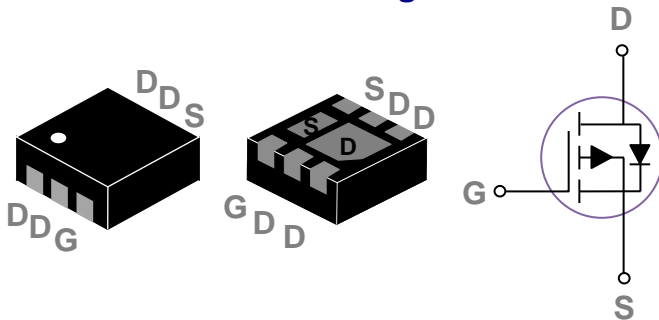
Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN2x2-6L 2EP Pin Configuration



BVDSS	RDSON	ID
-20V	12mΩ	-16A

Features

- -20V, -16A, $R_{DS(ON)} = 12m\Omega @ V_{GS} = -4.5V$
- Improved dv/dt capability
- Fast switching
- Green Device Available

Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	-16	A
	Drain Current – Continuous ($T_c=70^\circ\text{C}$)	-12	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	2.5	W
	Power Dissipation – Derate above 25°C	0.026	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 125	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	55	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	25	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)
Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1\text{mA}$	---	-0.02	---	$V/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-12V$, $V_{GS}=0V$, $T_J=25^\circ\text{C}$	---	---	-1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 10V$, $V_{DS}=0V$	---	---	± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5V$, $I_D=-10A$	---	12	18	m Ω
		$V_{GS}=-2.5V$, $I_D=-8A$	---	16	25	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=-250\mu A$	-0.4	-0.8	-1.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	2	---	$\text{mV}/^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=-6V$, $I_S=-7A$	---	8.4	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2, 3}	$V_{DS}=-10V$, $V_{GS}=-4.5V$, $I_D=-4A$	---	16.1	---	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	1.8	---	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	3.8	---	
$T_{d(on)}$	Turn-On Delay Time ^{2, 3}	$V_{DD}=-10V$, $V_{GS}=-4.5V$, $R_G=25\Omega$ $I_D=-1A$	---	8.2	---	nS
T_r	Rise Time ^{2, 3}		---	30	---	
$T_{d(off)}$	Turn-Off Delay Time ^{2, 3}		---	71.1	---	
T_f	Fall Time ^{2, 3}		---	19.8	---	
C_{iss}	Input Capacitance	$V_{DS}=-6V$, $V_{GS}=0V$, $F=1\text{MHz}$	---	1500	---	pF
C_{oss}	Output Capacitance		---	300	---	
C_{rss}	Reverse Transfer Capacitance		---	240	---	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	-16	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V$, $I_S=-3.5A$, $T_J=25^\circ\text{C}$	---	---	-1.2	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

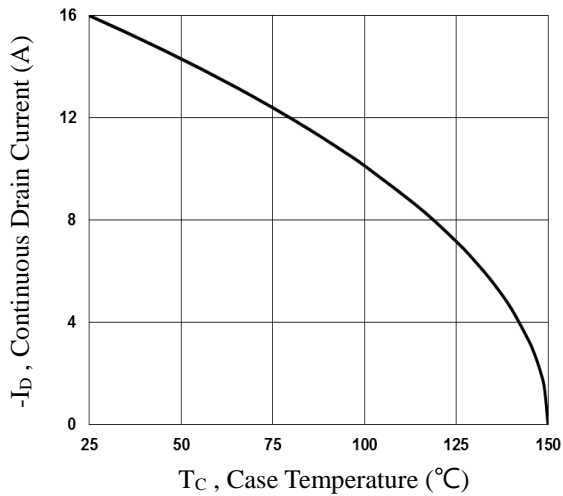


Fig.1 Continuous Drain Current vs. T_c

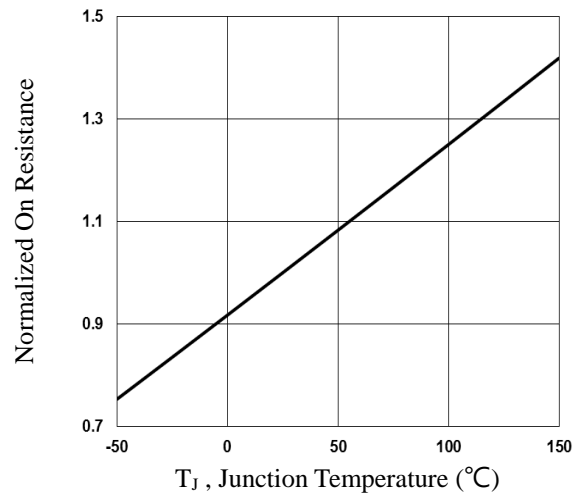


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

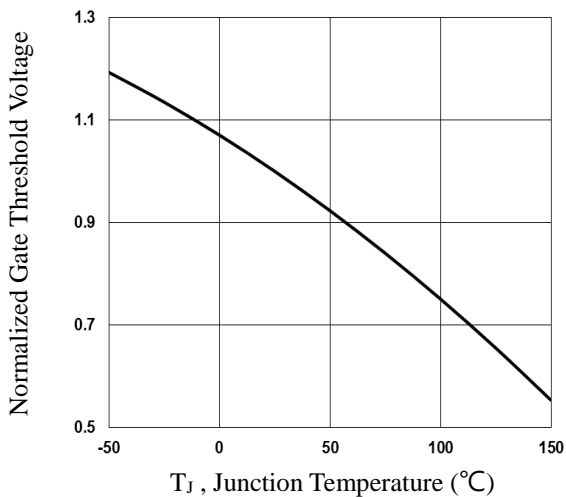


Fig.3 Normalized V_{th} vs. T_j

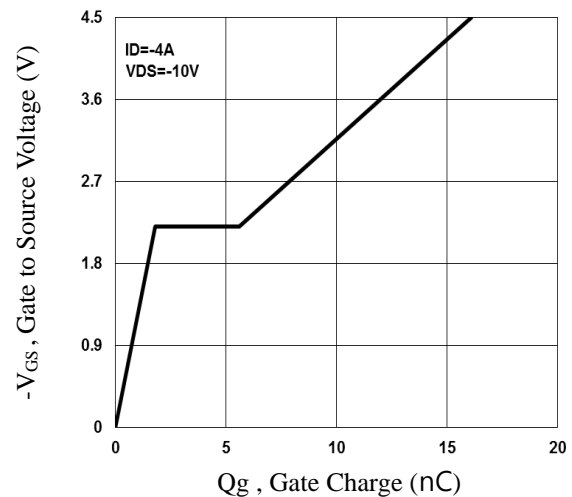


Fig.4 Gate Charge Waveform

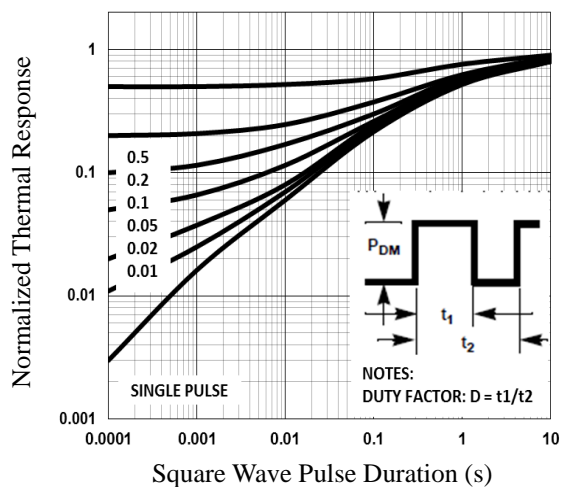


Fig.5 Normalized Transient Impedance

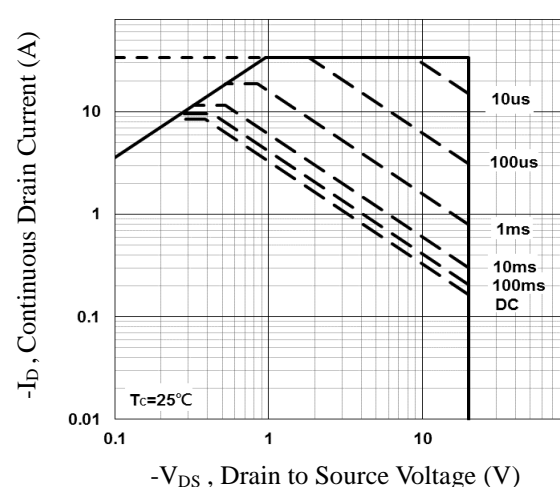


Fig.6 Maximum Safe Operation Area

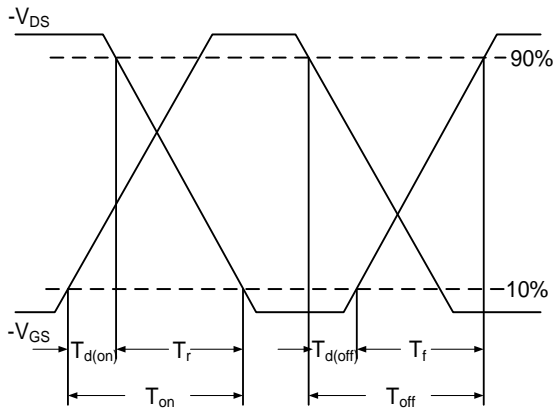


Fig.7 Switching Time Waveform

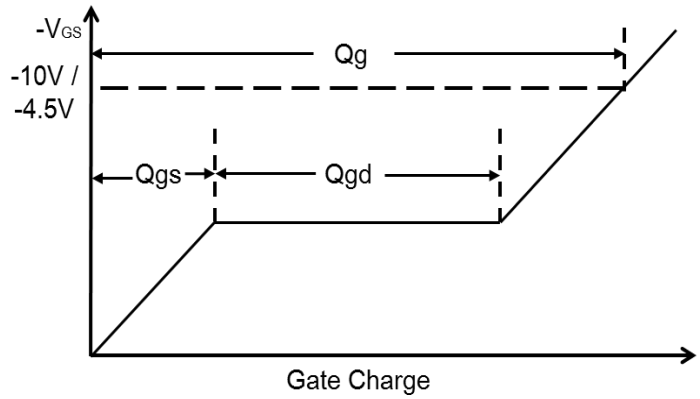
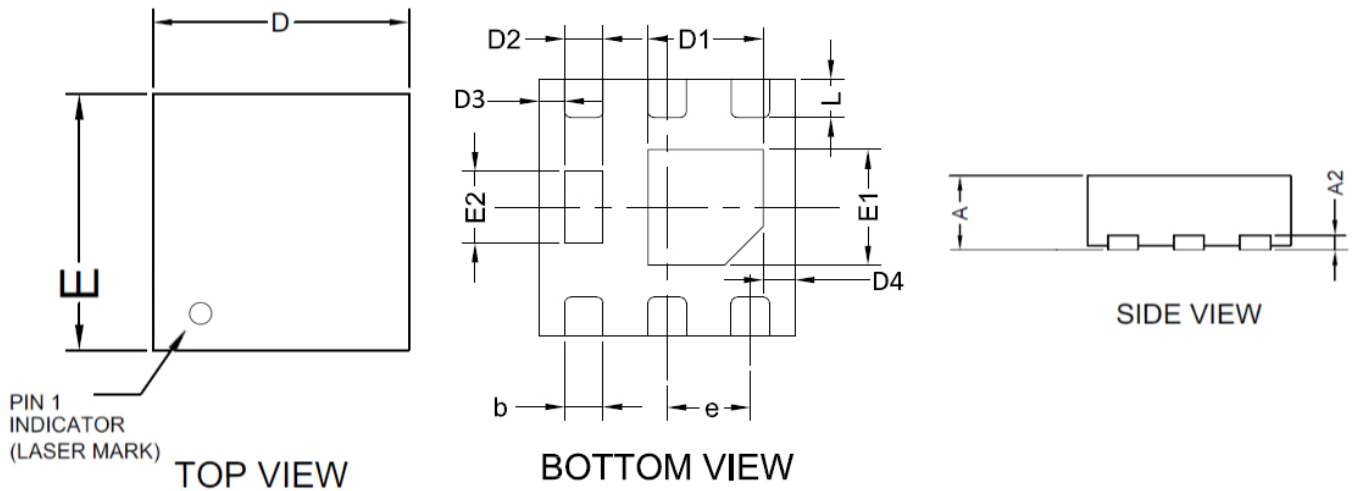


Fig.8 Gate Charge Waveform

DFN2x2-6L 2EP PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.800	0.500	0.031	0.019
A2	0.250	0.145	0.010	0.006
b	0.350	0.250	0.014	0.010
D	2.100	1.900	0.083	0.075
D1	1.000	0.800	0.040	0.031
D2	0.350	0.250	0.014	0.010
D3	0.200BSC		0.008BSC	
D4	0.200BSC		0.008BSC	
E	2.100	1.900	0.083	0.075
E1	1.050	0.800	0.041	0.031
E2	0.66	0.46	0.026	0.018
e	0.650BSC		0.026BSC	
L	0.350	0.250	0.014	0.010

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